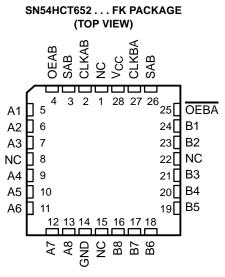
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- Operating Voltage Range of 4.5 V to 5.5 V
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible



			L
CLKAB	$ _1 \cup$	24	] V <sub>CC</sub>
SAB [	2	23	CLKBA
OEAB [	3	22	] SBA
A1 [	4	21	] OEBA
A2 [	5	20	] B1
A3 [	6	19	] B2
A4 [	7	18	] B3
A5 [	8	17	] B4
A6 [	9	16	] B5
A7 [	10	15	] B6
A8 [	11	14	] B7
GND [	12	13	] в8
			I

- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads



NC - No internal connection

### description/ordering information

The 'HCT652 devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select real-time or stored data transfer. A low input level selects real-time data; a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with these devices.

TA	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74HCT652NT	SN74HCT652NT
-40°C to 85°C	SOIC - DW	Tube	SN74HCT652DW	HCT652
	3010 - 010	Tape and reel	SN74HCT652DWR	HC1052
	CDIP – JT	Tube	SNJ54HCT652JT	SNJ54HCT652JT
–55°C to 125°C	CFP – W	Tube	SNJ54HCT652W	SNJ54HCT652W
	LCCC – FK	Tube	SNJ54HCT652FK	SNJ54HCT652FK

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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### SN54HCT652, SN74HCT652 **OCTAL BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS SCLS179D - MARCH 1984 - REVISED MARCH 2003

### description/ordering information (continued)

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) terminals, regardless of the select- or output-control terminals. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V<sub>CC</sub> through a pullup resistor and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

		INPU <sup>.</sup>	rs			DATA	A 1/0†	
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	н	$\uparrow$	$\uparrow$	Х	х	Input	Input	Store A and B data
Х	Н	$\uparrow$	H or L	Х	Х	Input	Unspecified <sup>‡</sup>	Store A, hold B
н	н	$\uparrow$	$\uparrow$	х‡	х	Input	Output	Store A in both registers
L	Х	H or L	Ŷ	Х	Х	Unspecified <sup>‡</sup>	Input	Hold A, store B
L	L	$\uparrow$	$\uparrow$	Х	x‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Х	H or L	Х	н	Output	Input	Stored B data to A bus
н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
н	Н	H or L	Х	н	Х	Input	Output	Stored A data to B bus
н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

**FUNCTION TABLE** 

<sup>†</sup> The data-output functions can be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.

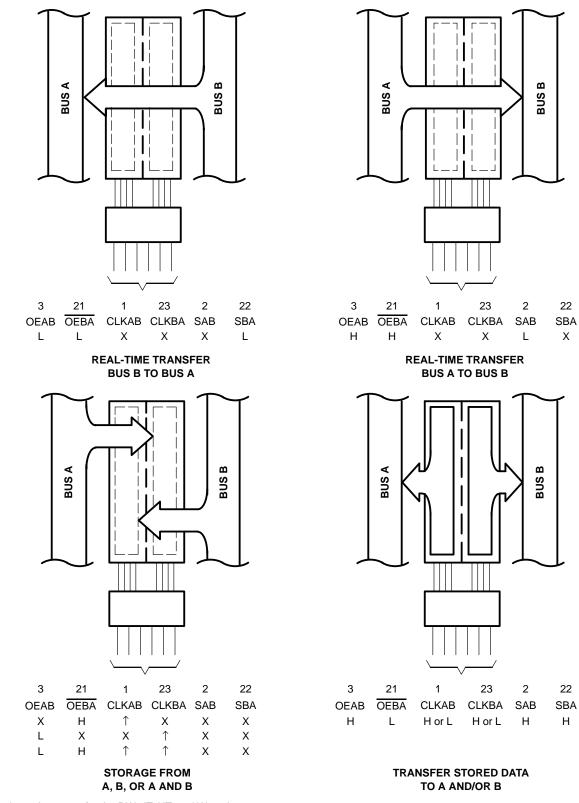
<sup>‡</sup> Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered to load both registers.





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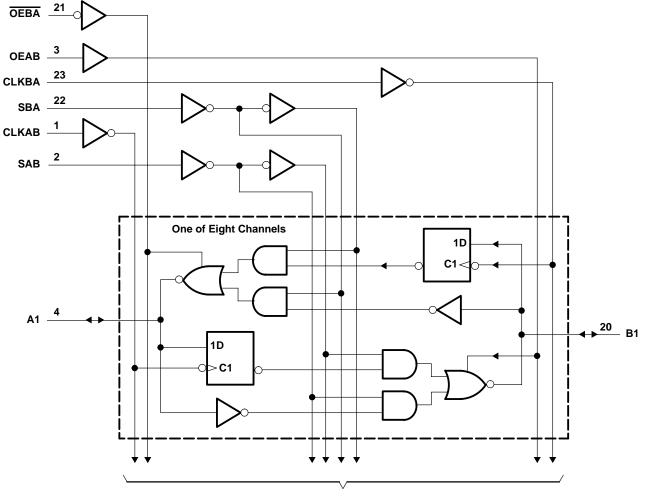
Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



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### logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DW, JT, NT, and W packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V <sub>CC</sub> or GND	±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	46°C/W
(see Note 3): NT package	67°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

3. The package thermal impedance is calculated in accordance with JESD 51-3.



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### recommended operating conditions (see Note 4)

			SN	54HCT6	52	SN	74HCT6	52	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	\$ 5.5	4.5	5	5.5	V
VIH	High-level input voltage	$V_{CC} = 4.5 V \text{ to } 5.5 V$	2		4	2			V
VIL	Low-level input voltage	$V_{CC} = 4.5 V \text{ to } 5.5 V$		PE	0.8			0.8	V
VI	Input voltage		0	7	VCC	0		VCC	V
Vo	Output voltage		0	50	VCC	0		VCC	V
tt	Input transition (rise and fall) time		Ó	2	500			500	ns
Т <sub>А</sub>	Operating free-air temperature		-55		125	-40		85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	RAMETER	TEST CO	NDITIONS	Vaa	Т	A = 25°C	;	SN54H	CT652	SN74H	CT652	UNIT
F#	ARAMETER	TEST CO	NDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
∨он		VI = VIH or VIL	I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
VОН		VI = VIH OL VIL	I <sub>OH</sub> = -6 mA	4.5 V	3.98	4.3		3.7		3.84		v
Vol		VI = VIH or VIL	I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL		VI = VIH OL VIL	$I_{OL} = 6 \text{ mA}$			0.17	0.26		0.4		0.33	v
Ц	Control inputs	$V_{I} = V_{CC} \text{ or } 0$	5.5 V		±0.1	±100		±1000		±1000	nA	
I <sub>OZ</sub>	A or B		$V_O = V_{CC}$ or 0, $V_I = V_{IH}$ or $V_{IL}$ , Data = $V_{CC}$ or 0			±0.01	±0.5	UCY VCY	±10		±5	μA
ICC		$V_{I} = V_{CC} \text{ or } 0,$	I <sub>O</sub> = 0	5.5 V			8	20	160		80	μA
∆ICC†	t	One input at 0.5 Other inputs at 0	5.5 V		1.4	2.4	P	3		2.9	mA	
Ci	Control inputs		4.5 V to 5.5 V		3	10		10		10	pF	

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		Vee	T <sub>A</sub> = 2	25°C	SN54H	CT652	SN74H	CT652	UNIT
		Vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
f	Clock frequency	4.5 V		25		17		20	MHz
fclock	Clock nequency	5.5 V		28		19		22	
+	Pulse duration, CLKBA or CLKAB high or low	4.5 V	20		30	EL	25		ns
t <sub>w</sub>	Fuse duration, CENDA of CENAD high of low	5.5 V	18		27	4	23		115
		4.5 V	15		23		19		
t <sub>su</sub>	Setup time, A before CLKAB↑ or B before CLKBA↑	5.5 V	14		21		17		ns
+.	Hold time, A after CLKAB↑ or B after CLKBA↑	4.5 V	5		5		5		ns
th	Hold liftle, A alter CERAB   OF B alter CERBA	5.5 V	5		5		5		115



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# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	Vaa	Т	ן = 25°C	;	SN54H	CT652	SN74H	CT652	UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f			4.5 V	25	35		17		20		MHz
fmax			5.5 V	28	40		19		22		
	CLKBA or CLKAB	A or B	4.5 V		18	36		54		45	
	CENDA OF CENAD	AUB	5.5 V		16	32		49		41	
<b>•</b> .	A or B	B or A	4.5 V		14	27		41		34	-
<sup>t</sup> pd A or	AUB	BUIA	5.5 V		12	24		37		31	ns
	004 040 <sup>+</sup>	A or B	4.5 V		20	38	6	57		48	
	SBA or SAB <sup>†</sup>	AUB	5.5 V		17	34	ng	51		43	
+		A or B	4.5 V		25	49	6	74		61	20
ten	OEBA or OEAB	AUB	5.5 V		22	44	2	67		55	ns
<b>•</b>		A or B	4.5 V		25	49		74		61	
<sup>t</sup> dis	OEBA or OEAB	AUD	5.5 V		22	44		67		55	ns
<b>4</b> .		Ap.(	4.5 V		9	12		18		15	
tt		Any	5.5 V		7	11		16		14	ns

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

# switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 2)

DADAMETED	FROM	то	Vaa	Т,	ן = 25°C	;	SN54H	CT652	SN74H	CT652	
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	CLKBA or CLKAB	A or B	4.5 V		24	53		80		66	
	CLKBA UI CLKAB	AUIB	5.5 V		22	47		72		60	
<b>.</b> .	A or B	B or A	4.5 V		22	44		70		55	ns
<sup>t</sup> pd		BUIA	5.5 V		20	39		60		50	115
		A or B	4.5 V		26	55	4	83		69	
	SBA or SAB†	AUB	5.5 V		24	49	$\mathcal{D}_{\mathcal{D}}$	74		62	
+		A or B	4.5 V		33	66	702	100		82	ns
t <sub>en</sub>	OEBA or OEAB	AUIB	5.5 V		30	59	d	90		74	115
+.	A. 201		4.5 V		17	42		63		53	20
tt		Any	5.5 V		14	38		57		48	ns

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

# operating characteristics, $T_A = 25^{\circ}C$

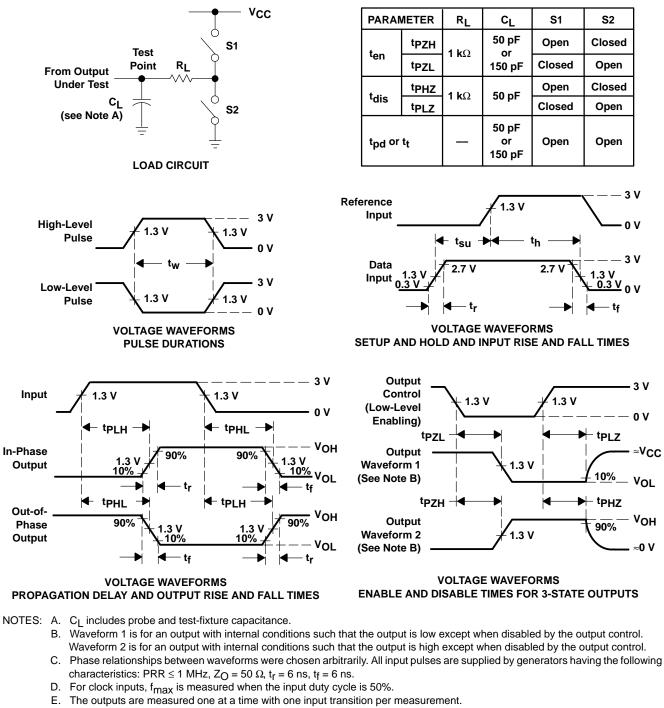
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	50	pF

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#### PARAMETER MEASUREMENT INFORMATION



- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HCT652DW	LIFEBUY	SOIC	DW	24	25	RoHS & Green	(6) NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT652	
SN74HCT652DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT652	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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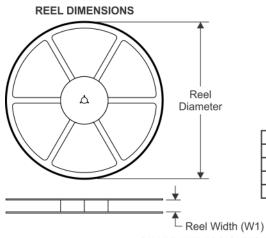
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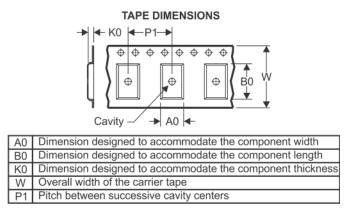
# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	· · /	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT652DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1



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# PACKAGE MATERIALS INFORMATION

5-Jan-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT652DWR	SOIC	DW	24	2000	350.0	350.0	43.0



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5-Jan-2022

## TUBE

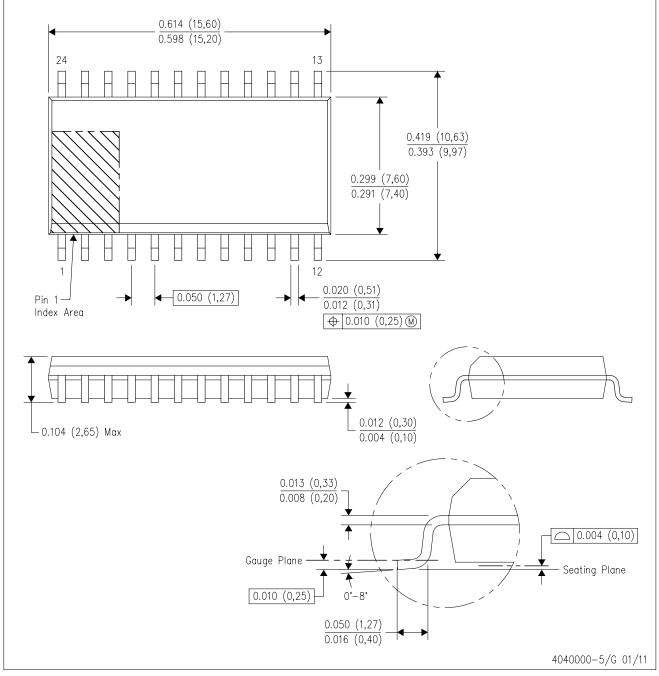


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74HCT652DW	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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